IPC  ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard  http://www.ipc.org/IPC-175x  Form Typ Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier Infor	mation								,					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2025-06-06			
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Reques	ster Item Number			Mfr Item Name			Effective Date	Version	N	Manufacturing Site	V	Veight*	UOM	Unit Type
				BIP PWR XTSR 8A	3A/80V LFPAK56		2025-06-06	-06-06 PBB		PBB	74.911		mg	Each
	g Process Informati			A.11	CTD 020 MCI	I. Dating	De els Dece	D - 1 7	,	Mary Times at Death	T	N. N. N.	f D . fl C	
ž ž		,		STD-020 MSI	L Rating	Peak Process Body Ten		emperatur				er of Reflow Cyc	cles	
•	Tin (Sn) - annealed	C	U Alloy				260		IC	30	secon	ds 3		
omments			1	0 1										
	time at peak temperatur													
r more informa	tion regarding material c	composition p	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-6_									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	3.7	mg	Supplier	Iron (Fe)	7439-89-6		0.0044	mg
			Supplier	Copper (Cu)	7440-50-8		3.6944	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0011	mg
Die	0.5	mg	Supplier	Silicon (Si)	7440-21-3		0.5	mg
Lead Frame	33.4	mg	Supplier	Silver (Ag)	7440-22-4		0.0033	mg
			Supplier	Iron (Fe)	7439-89-6		0.0401	mg
			Supplier	Copper (Cu)	7440-50-8		33.3466	mg
			Supplier	Phosphorus (P)	7723-14-0		0.01	mg
Mold Compound-Black	31.9	mg	Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.1595	mg
			Supplier	Boron zinc hydroxide oxide	138265-88-0		4.785	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.785	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0797	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.3363	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.7545	mg
Plating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Solder Paste	3.7	mg	Supplier	Silver (Ag)	7440-22-4		0.0925	mg
			A	Lead (Pb)	7439-92-1	7a	3.4225	mg
			Supplier	Tin (Sn)	7440-31-5		0.185	mg
Wire Bond - Cu	0.011	mg	Supplier	Copper (Cu)	7440-50-8		0.011	mg